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Always follow TI’s set-up and application instructions, including use of all interface components within their recommended electrical rated voltage and power limits. Always use electrical safety precautions to help ensure your personal safety and the safety of those working around you. Contact TI’s Product Information Center http://support.ti.com for further information.

Save all warnings and instructions for future reference.

Failure to follow warnings and instructions may result in personal injury, property damage, or death due to electrical shock and/or burn hazards.

The term TI HV EVM refers to an electronic device typically provided as an open framed, unenclosed printed circuit board assembly. It is intended strictly for use in development laboratory environments, solely for qualified professional users having training, expertise, and knowledge of electrical safety risks in development and application of high-voltage electrical circuits. Any other use and/or application are strictly prohibited by Texas Instruments. If you are not suitably qualified, you should immediately stop from further use of the HV EVM.

• **Work Area Safety:**
  - Maintain a clean and orderly work area.
  - Qualified observer(s) must be present anytime circuits are energized.
  - Effective barriers and signage must be present in the area where the TI HV EVM and its interface electronics are energized, indicating operation of accessible high voltages may be present, for the purpose of protecting inadvertent access.
  - All interface circuits, power supplies, evaluation modules, instruments, meters, scopes and other related apparatus used in a development environment exceeding 50 V<sub>RMS</sub>/75 V<sub>DC</sub> must be electrically located within a protected Emergency Power Off (EPO) protected power strip.
  - Use a stable and non-conductive work surface.
  - Use adequately insulated clamps and wires to attach measurement probes and instruments. No freehand testing whenever possible.

• **Electrical Safety:**
  - As a precautionary measure, it is always a good engineering practice to assume that the entire EVM may have fully accessible and active high voltages.
  - De-energize the TI HV EVM and all its inputs, outputs, and electrical loads before performing any electrical or other diagnostic measurements. Confirm that TI HV EVM power has been safely de-energized.
  - With the EVM confirmed de-energized, proceed with required electrical circuit configurations, wiring, measurement equipment hook-ups and other application needs, while still assuming the EVM circuit and measuring instruments are electrically live.
  - When EVM readiness is complete, energize the EVM as intended.

**WARNING:** While the EVM is energized, never touch the EVM or its electrical circuits as they could be at high voltages capable of causing electrical shock hazard.
• **Personal Safety:**  
  – Wear personal protective equipment, for example, latex gloves and/or safety glasses with side shields or protect EVM in an adequate lucent plastic box with interlocks from accidental touch.

• **Limitation for Safe Use:**  
  – EVMs are not to be used as all or part of a production unit.

**Safety and Precautions**

The EVM is designed for professionals who have received the appropriate technical training, and is designed to operate from an AC power supply or a high-voltage DC supply. Please read this user guide and the safety-related documents that come with the EVM package before operating this EVM.

**CAUTION**

Do not leave the EVM powered when unattended.

**WARNING**

Hot surface! Contact may cause burns. Do not touch!

**WARNING**

High Voltage! Electric shock is possible when connecting board to live wire. Board should be handled with care by a professional.  
For safety, use of isolated test equipment with overvoltage and overcurrent protection is highly recommended.
Using the LMG5200EVM-01A GaN Half-Bridge Power Stage EVM

The LMG5200 device is a 80-V Gallium Nitride (GaN) half-bridge power module with an integrated driver. It provides an integrated power stage solution using enhancement-mode GaN FETs. The LMG5200 device consists of two GaN FETs driven by one high-frequency GaN FET driver in a half-bridge configuration. The guide shows a circuit and the list of materials describing how to power the board up and how to set the board up for a certain regulation voltage. The EVM board is designed to accelerate the evaluation of the LMG5200. This board is not intended to be used as a standalone product but it intended to evaluate the switching performance of LMG5200.

1 Description

The LMG5200 evaluation module is a small, easy-to-use power stage with an external PWM signal. The board can be configured as a buck converter, boost converter or other converter topology using a half bridge. Because this is an open loop board with an external PWM signal, do not use it to evaluate transient response. It can be used to evaluate the performance of the LMG5200 as a hard-switched converter to sample measurements such as efficiency, switching speed and dv/dt. The EVM features a LMG5200 half-bridge power module with two 18-mΩ GaN FETs and a half-bridge driver. The module can deliver up to 10 A of current if the application includes adequate thermal management (monitor case temperature and ensure adequate airflow is present if required). The thermal management considerations include forced air, heat sink and lower operating frequency in order to minimize the power dissipation in the module.

1.1 Featured Application

LMG5200EVM-01A features include:

- Input voltage operates up to 80 V DC
- Integrated 80-V, 18-mΩ GaN FET with driver
- Single-input, on-board for PWM signal with 8 ns dead time
- Configurable on-board dead-time adjustment by simple resistance change
- On-board LDO for generating 5-V VCC supply from a poorly regulated supply between 5.5 V and 6.5 V
- Kelvin sense capability for efficiency measurements for input and output voltage

CAUTION

High-voltage levels are present on the evaluation module whenever it is energized. Proper precautions must be taken when working with the EVM.

1.2 Typical Applications

The LMG5200 is suited for use in high frequency DC-DC converters converters. It is simple to use and has a low-external component count.

- High-speed, synchronous buck converters
- Class D amplifiers for audio
- 48-V point-of-load converters for industrial, computing and telecom
Figure 1 shows the schematic of the EVM.
3 EVM Kit Contents
The kit contains the following:
• Using the LMG5200 GaN Half-Bridge Power Module EVM (this user's guide)
• Safety instructions
• LMG5200 specifications

4 Electrical Performance Specifications
The inductor used in this EVM is a 4.7-µH inductor. The switching frequency is set by an external PWM
signal (between 0 V and 5 V). The duty cycle of this PWM signal sets the duty cycle of the half-bridge
module.

4.1 Test Setup
Figure 2 and the procedure to setup the hardware for evaluation.

WARNING
High voltages that may cause injury exist on this evaluation
module (EVM). Please ensure all safety procedures are followed
when working on this EVM. Never leave a powered EVM
unattended.
4.1.1 List of Test Points

Table 1. Test Point Functional Description

<table>
<thead>
<tr>
<th>TEST POINT</th>
<th>NAME</th>
<th>DESCRIPTION</th>
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</thead>
<tbody>
<tr>
<td>TP1</td>
<td>TP1</td>
<td>Sense connection for the input supply</td>
</tr>
<tr>
<td>TP2</td>
<td>TP2</td>
<td>Sense connection for output voltage</td>
</tr>
<tr>
<td>TP3</td>
<td>TP3</td>
<td>Sense connection for output ground</td>
</tr>
<tr>
<td>TP4</td>
<td>TP4</td>
<td>Analog Ground sense connection</td>
</tr>
<tr>
<td>TP6</td>
<td>TP6</td>
<td>5V sense connection for LDO output</td>
</tr>
<tr>
<td>TP7</td>
<td>TP7</td>
<td>Sense connection for the input supply ground</td>
</tr>
<tr>
<td>TP9</td>
<td>TP9</td>
<td>HI input to LMG5200</td>
</tr>
<tr>
<td>TP10</td>
<td>TP10</td>
<td>LO input to LMG5200</td>
</tr>
<tr>
<td>J1</td>
<td>J1</td>
<td>VIN power connector (10-60V DC)</td>
</tr>
<tr>
<td>J2</td>
<td>J2</td>
<td>VOUT power connector (5-20V, 10A)</td>
</tr>
<tr>
<td>J3</td>
<td>J3</td>
<td>EXTVCC connection (5.5V-6.5V)</td>
</tr>
</tbody>
</table>

4.1.2 Key Connections

The following test procedure is recommended primarily for powering up and shutting down the evaluation module. Never leave a powered EVM unattended for any length of time. Also, the unit should never be handled while power is applied to it.

**WARNING**

There are very high voltages present on the EVM. Some components reach temperatures above 50°C. Precautions must be taken when handling the board.

4.1.2.1 Connect a Supply to J3 Connector

There is the bias supply EXTVCC (between 5.5 V and 6.5 V) for the LMG5200 driver. This driver supply is regulated to 5 V by the series LDO U2 (LP3869). This regulation ensures that the bias supply for the LMG5200 is accurate and is not exceeded beyond the gate voltage specifications. This User’s Guide refers to this supply as the driver bias supply. It is critical to ensure that the EXTVCC supply is powered up before the VIN supply (J1) to ensure safe operation. Similarly during power down, it is important to ensure that the VIN supply (J1) is powered down before the bias supply (EXTVCC).

4.1.2.2 PWM Input

Provide the PWM input using a function generator that is capable of providing the desired switching frequency and duty cycle. This function generator output should be connected to the J5 connector as shown in the Figure 4. The red arrow shows +Ve the and black arrows show the GND PWM connections. Pin 4 is the positive input of the PWM supply and the remaining three pins are GND pins in the default state of the board.
4.1.2.3 J1 Connector

Connect the input voltage to the J1 connector ensure that the +ve and –ve supply is connected appropriately - the +ve and -ve terminals are marked on the board. The sense connection for the input supply is via the TP1 and TP7 test points respectively. This is useful when doing efficiency calculations as this will ensure that the resistive losses to the board are taken into account and the losses calculated are related to the board and the LMG5200 half bridge.

The output load is connected to the J2 connector. The +ve and –ve sense signals are TP2 and TP3 respectively.

4.1.3 Power-Up Procedure

4.1.3.1 Step 1: Driver Bias Supply

Power up the driver bias supply (5.5 V to 6.5 V) first. The D1 diode lights up after the driver bias supply comes up. After this step, observe the PWM signals on test points TP9 and TP10. Insure that the PWM signal for the high and low side are of the desired frequency (100 kHz to 5MHz depending on the input voltage and load). Also observe the default dead time between the high-to-low and low-to-high PWM transitions.
4.1.3.2 Step 2: Input Supply

Power up the input supply (10 V to 60 V). The D2 diode lights up after the input supply is powered up.

Observe the output voltage on the sense signals (TP2, TP3). Adjust the PWM duty cycle such that the output is of the desired voltage. Load the output with an appropriate electronic load.

NOTE: The PWM duty cycle must be adjusted to compensate for the losses when the supply is loaded.

4.1.3.3 Step 3

To observe the SW node connect a probe with a small pigtail to the via next to the SW pin, as shown in Figure 5. This ensures that the measurement loop is small and hence accurately reflects the behavior of the SW node. If a large loop is used to the high dv/dt on the SW node and the parasitic impedance (inductance) of the loop a large amount of ringing will be observed on the SW node which is not representative of the device performance but is measurement artifact. The probe connection should be made prior to the board being powered up and one should ensure that appropriate safety precautions are taken.

Connect the scope probe to measure the SW node as shown in Figure 5. Notice the small pigtail used to minimize the ground loop as shown in Figure 6.

**Figure 5. Measuring the SW Node**

**Figure 6. Small GND Loop**

4.1.3.4 Setting Dead-Time

Dead times are set by the RC delays between the inverted and non-inverted PWM input connected to jumper J3. The dead time typically does not require to be changed, however to evaluate impact of dead time on efficiency, you can vary the RC delay, its easy to change resistors R14 and R2 to get the appropriate dead time. Ensure that the dead time is not reduced so much that it causes a shoot-through condition.
4.1.4 Power-Down Procedure

To power down the board the power up procedures should be followed in reverse. Hence the load should be turned off first. Next the input supply should be turned off. Followed by the PWM signal and finally the driver bias supply.

4.2 Results

![Figure 7. SW Node Behavior Showing the Dead Time and the Overshoot in the SW Node](image1)

![Figure 8. Zoom in of the SW Node Showing the Dead Time of 7.7-ns (Converter Loaded With 2 A)](image2)

NOTE: Visit the [E2E forum Gallium Nitride Solutions](https://e2e.ti.com) for more information regarding LMG5200 or LMG5200 hard-switched EVM.
## List of Materials

### Table 2. LMG5200EVM-01A List of Materials

<table>
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<tr>
<th>Designator</th>
<th>Quantity</th>
<th>Value</th>
<th>Description</th>
<th>Package Reference</th>
<th>Part Number</th>
<th>Manufacturer</th>
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<td>MuRata</td>
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<td>C4, C5, C6, C7, C12, C13</td>
<td>6</td>
<td>2.2 µF</td>
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<td>MuRata</td>
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<td>C11</td>
<td>±10%, X7R, 0603</td>
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<td>C2, C9, C14</td>
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<td>0603YC104JAT2A</td>
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<td>10 µF</td>
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<td>2.2 µF</td>
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<td>C0805C225K4RACTU</td>
<td>Kemet</td>
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<td>40 V</td>
<td>Diode, Schottky, 40 V, 0.03A, SOD-523</td>
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<td>Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead</td>
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<td>NY PMS 440 0025 PH</td>
<td>B&amp;F Fastener Supply</td>
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<td>Standoff, Hex, 0.5&quot;L #4-40 Nylon</td>
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<td>1902C</td>
<td>Keystone</td>
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<td>J1, J2</td>
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<td>Terminal Block, 2x1, 5.08mm, TH</td>
<td>10.16x15.2x9mm</td>
<td>282841-2</td>
<td>TE Connectivity</td>
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<td>J3</td>
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<td>L1</td>
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<td>4.7 µH</td>
<td>Inductor, Shielded, Composite, 4.7uH, 10.5A, 8.89 ohm, SMD</td>
<td>8.1 x 8 x 8.6mm</td>
<td>XAL8080-472ME</td>
<td>Coilcraft</td>
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(1) Unless otherwise noted, all parts may be substituted with equivalents.
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<th>Value</th>
<th>Description</th>
<th>Package Reference</th>
<th>Part Number</th>
<th>Manufacturer</th>
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<td>1.0 kΩ</td>
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<td>CRCW06031K00JNEA</td>
<td>Vishay-Dale</td>
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<td>R2, R14</td>
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<td>47</td>
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<td>Keystone</td>
</tr>
<tr>
<td>U1</td>
<td>1</td>
<td>LMG5200AMOF, MOF0009A</td>
<td>MOF0009A</td>
<td>LMG5200AMOF</td>
<td>Texas Instruments</td>
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<td>U2</td>
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<td>1-A Low Dropout CMOS Linear Regulators, 6-pin LLP</td>
<td>SDE06A</td>
<td>LP38690SD-5.0</td>
<td>Texas Instruments</td>
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<td>U3</td>
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<td>IC, Tripple Schmitt-Trigger Inverter</td>
<td>VSSOP</td>
<td>SN74LVC3G14DCU</td>
<td>Texas Instruments</td>
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<td>U4</td>
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<td>WCSP-6</td>
<td>SN74LVC2G14YZPR</td>
<td>Texas Instruments</td>
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<td>Resistor, 0 ohm, 5%, 0.063W, 0402</td>
<td>0402</td>
<td>CRCW04020000Z0ED</td>
<td>Vishay-Dale</td>
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</tbody>
</table>

(2) No alternate component manufacturer.
STANDARD TERMS AND CONDITIONS FOR EVALUATION MODULES

1. **Delivery:** TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, or documentation (collectively, an “EVM” or “EVMs”) to the User (“User”) in accordance with the terms and conditions set forth herein. Acceptance of the EVM is expressly subject to the following terms and conditions.

   1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductors products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM (“Software”) shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms and conditions that accompany such Software.

   1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.

2. **Limited Warranty and Related Remedies/Disclaimers:**

   2.1 These terms and conditions do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.

   2.2 TI warrants that the TI EVM will conform to TI’s published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for any defects that are caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI. Moreover, TI shall not be liable for any defects that result from User's design, specifications or instructions for such EVMs. Testing and other quality control techniques are used to the extent TI deems necessary or as mandated by government requirements. TI does not test all parameters of each EVM.

   2.3 If any EVM fails to conform to the warranty set forth above, TI’s sole liability shall be at its option to repair or replace such EVM, or credit User’s account for such EVM. TI’s liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.

3. **Regulatory Notices:**

   3.1 United States

      3.1.1 Notice applicable to EVMs not FCC-Approved:

      This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

      3.1.2 For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:

      **CAUTION**

      This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

      Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

      **FCC Interference Statement for Class A EVM devices**

      NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.
FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

3.3 Japan

3.3.1 Notice for EVMs delivered in Japan: Please see http://www.tij.co.jp/lsds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lsds/ti_ja/general/eStore/notice_01.page

3.3.2 Notice for Users of EVMs Considered “Radio Frequency Products” in Japan: EVMs entering Japan are NOT certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, User is required by Radio Law of Japan to follow the instructions below with respect to EVMs:

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.
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4 EVM Use Restrictions and Warnings:
4.1 EVMs are not for use in functional safety and/or safety critical evaluations, including but not limited to evaluations of life support applications.
4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.
4.3 Safety-Related Warnings and Restrictions:
4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.
4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.
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5. Accuracy of Information: To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.
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